

4. (Amended) The printed wiring board according to claim 1, wherein said plated layer contains tin.

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A3 5. (Amended) The printed wiring board according to claim 1, wherein said plated layer contains nickel.

Sub B2 6. (Amended) The printed wiring board according to any one of claims 1, 4 and 5, wherein said heat radiating means is made of metal, and is provided, on a rear side thereof, with an attaching plate which is able to be brought into contact with said circuit board on a rear side thereof and on a front side thereof, with a plurality of fins for radiating heat.

7. (Amended) The printed wiring board according to claim 6, wherein said plurality of fins for radiating heat forms a corrugated cross-section being uniformly shaped in such a way that a long-length of a belt-shaped hoop material is extruded and cut at prescribed length.

A4 10. (Amended) The printed wiring board according to claim 1, wherein said first heat radiating pattern and said heat radiating plate are connected to each other via through-holes which pass through said circuit board.

11. (Amended) The printed wiring board according to claim 1, wherein said first heat radiating pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit board.

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12. (Amended) The printed wiring board according to claim 1, wherein said second heat radiating pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit board.

13. (Amended) The printed wiring board according to claim 6, wherein said fins of said heat radiating means are designed to stand with respect to the circuit board.

Please add new claims 15-22 as follows:

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15. A printed wiring board, comprising:
a circuit board;
an electronic component mounted on said circuit board and including a heat radiating plate for conducting heat internally generated;
a first heat radiating pattern for conducting heat formed at a position on a front surface of said circuit board corresponding to said electronic component, such that the heat radiating plate of said electronic component is connected to said first heat radiating pattern by soldering;
a second heat radiating pattern for conducting heat formed at a position on a rear surface of said circuit board corresponding to said electronic component;

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a plated layer to which said second heat radiating pattern is soldered; and
heat radiating means mounted at a position corresponding to said electronic component
on the rear surface of said circuit board, such that said heat radiating means is mounted on said
circuit board via said plated layer.

16. The printed wiring board according to claim 15, wherein said plated layer
contains tin.

17. The printed wiring board according to claim 15, wherein said plated layer
contains nickel.

18. The printed wiring board according to claim 15, wherein said plated layer
includes a first layer containing nickel and a second layer containing tin.

19. The printed wiring board according to any one of claims 15 to 17, wherein said
heat radiating means is made of metal and includes a plurality of fins for radiating heat.

20. The printed wiring board according to claim 15, wherein said first heat radiating
pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit
board.

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21. The printed wiring board according to claim 15, wherein said second heat radiating pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit board.

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22. The printed wiring board according to claim 15, wherein said first heat radiating pattern and said second heat radiating pattern are connected via at least one through hole in heat, and an inner surface of the through hole is covered with a material having a specific heat smaller than that of the printed wiring board.
